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# TVS Diodes

Transient Voltage Suppressor Diodes

## ESD3V3U1U Series

Uni-directional Ultra-low Capacitance ESD / Transient Protection Diode

ESD3V3U1U-02LS  
ESD3V3U1U-02LRH

## Data Sheet

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Final

Industrial and Multi-Market

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**Revision History**

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# 1 Uni-directional Ultra-low Capacitance ESD / Transient Protection Diode

## 1.1 Features

- ESD / Transient protection of high speed data lines exceeding
  - IEC61000-4-2 (ESD):  $\pm 20$  kV (air / contact)
  - IEC61000-4-4 (EFT): 2.5 kV / 50 A (5/50 ns)
  - IEC61000-4-5 (surge): 3 A (8/20  $\mu$ s)
- Maximum working voltage:  $V_{RWM} = 3.3$  V
- Ultra low capacitance:  $C_L = 0.4$  pF (typical)
- Low clamping voltage, low dynamic resistance  $R_{DYN} = 0.6 \Omega$  (typical)
- Pb-free (RoHS compliant) and halogen free package, very small form factor down to  $0.62 \times 0.32 \times 0.31$  mm<sup>3</sup>



## 1.2 Application Examples

- HDMI, USB 2.0/USB 3.0, DisplayPort, DVI
- 10/100/1000 Ethernet, Firewire, S-ATA
- Mobile HDMI Link, MDDI, MIPI, etc.

# 2 Product Description

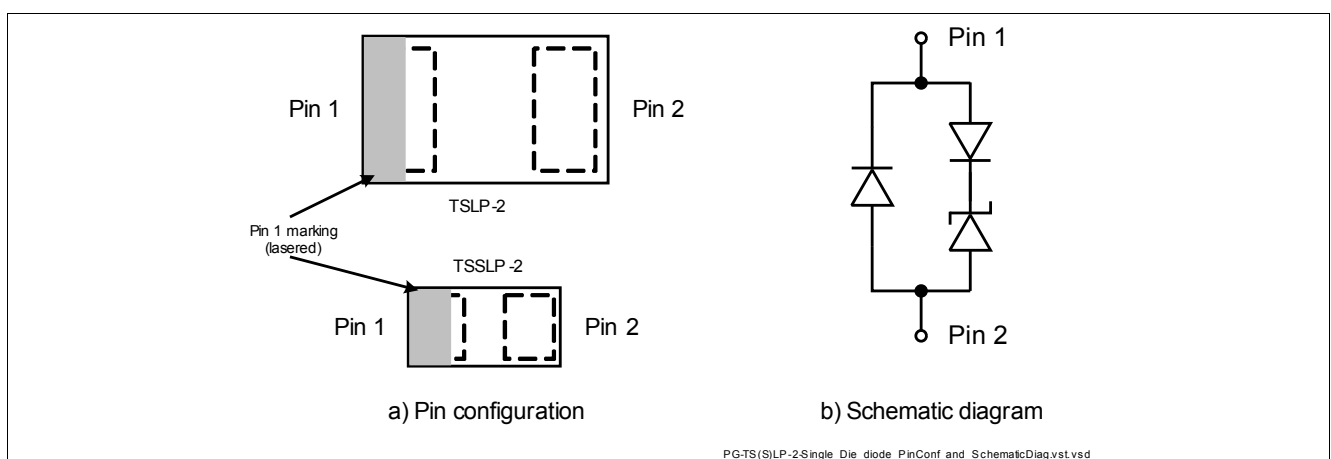


Figure 1 Pin Configuration and Schematic Diagram

Table 1 Ordering Information

Type	Package	Configuration	Marking code
ESD3V3U1U-02LS	PG-TSSLP-2-1	1 line, uni-directional	Z
ESD3V3U1U-02LRH	PG-TSLP-2-7	1 line, uni-directional	E3



### 3 Characteristics

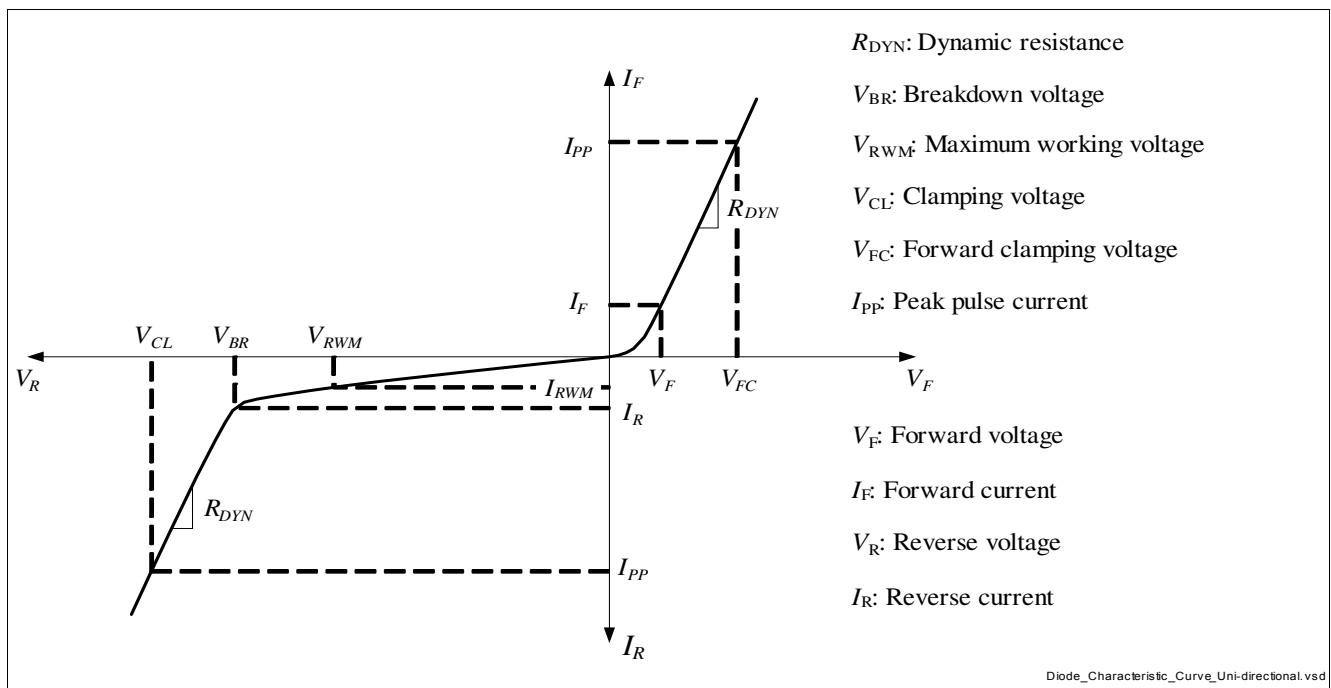
**Table 2** Maximum Rating at  $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
ESD (air / contact) discharge <sup>1)</sup>	$V_{ESD}$	–	–	20	kV
Peak pulse current ( $t_p = 8/20\text{ }\mu\text{s}$ ) <sup>2)</sup>	$I_{PP}$	–	–	3	A
Operating temperature range	$T_{OP}$	-55	–	125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-65	–	150	$^\circ\text{C}$

1)  $V_{ESD}$  according to IEC61000-4-2

2)  $I_{PP}$  according to IEC61000-4-5

#### 3.1 Electrical Characteristics at $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified



**Figure 2** Definitions of Electrical Characteristics

**Table 3** DC Characteristics at  $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Reverse working voltage	$V_{RWM}$	–	–	3.3	V	Pin 1 to Pin 2
Breakdown voltage	$V_{BR}$	5	–	–	V	$I_{BR} = 1\text{ mA}$ , from Pin 1 to Pin 2
Reverse current	$I_R$	–	<1	50	nA	$V_R = 3.3\text{ V}$ , from Pin 1 to Pin 2

**Table 4 RF Characteristics at  $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Line capacitance <sup>1)</sup>	$C_L$	–	0.4	0.6	pF	$V_R = 0\text{ V}, f = 1\text{ MHz}$
Serie inductance	$L_S$	–	0.2	–	nH	ESD3V3U1U-02LS
		–	0.4	–	nH	ESD3V3U1U-02LRH

1) Total capacitance line to ground

**Table 5 ESD Characteristics at  $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Clamping voltage	$V_{CL}$	–	19	–	V	$I_{PP} = 16\text{ A}$ , from Pin 1 to Pin 2
		–	28	–	V	$I_{PP} = 30\text{ A}$ , from Pin 1 to Pin 2
Forward clamping voltage	$V_{FC}$	–	10	–	V	$I_{PP} = 16\text{ A}$ , from Pin 2 to Pin 1
		–	17	–	V	$I_{PP} = 30\text{ A}$ , from Pin 2 to Pin 1
Dynamic resistance <sup>1)</sup>	$R_{DYN}$	–	0.6	–	$\Omega$	Pin 1 to Pin 2
		–	0.5	–	$\Omega$	Pin 2 to Pin 1

1) Please refer to Application Note AN210. TLP parameter:  $Z_0 = 50\ \Omega$ ,  $t_p = 100\text{ ns}$ ,  $t_r = 300\text{ ps}$ , averaging window:  $t_1 = 30\text{ ns}$  to  $t_2 = 60\text{ ns}$ , extraction of dynamic resistance using least squares fit of TLP characteristics between  $I_{PP1} = 10\text{ A}$  and  $I_{PP2} = 40\text{ A}$ .

3.2 Typical Characteristics at  $T_A=25^\circ\text{C}$ , unless otherwise specified

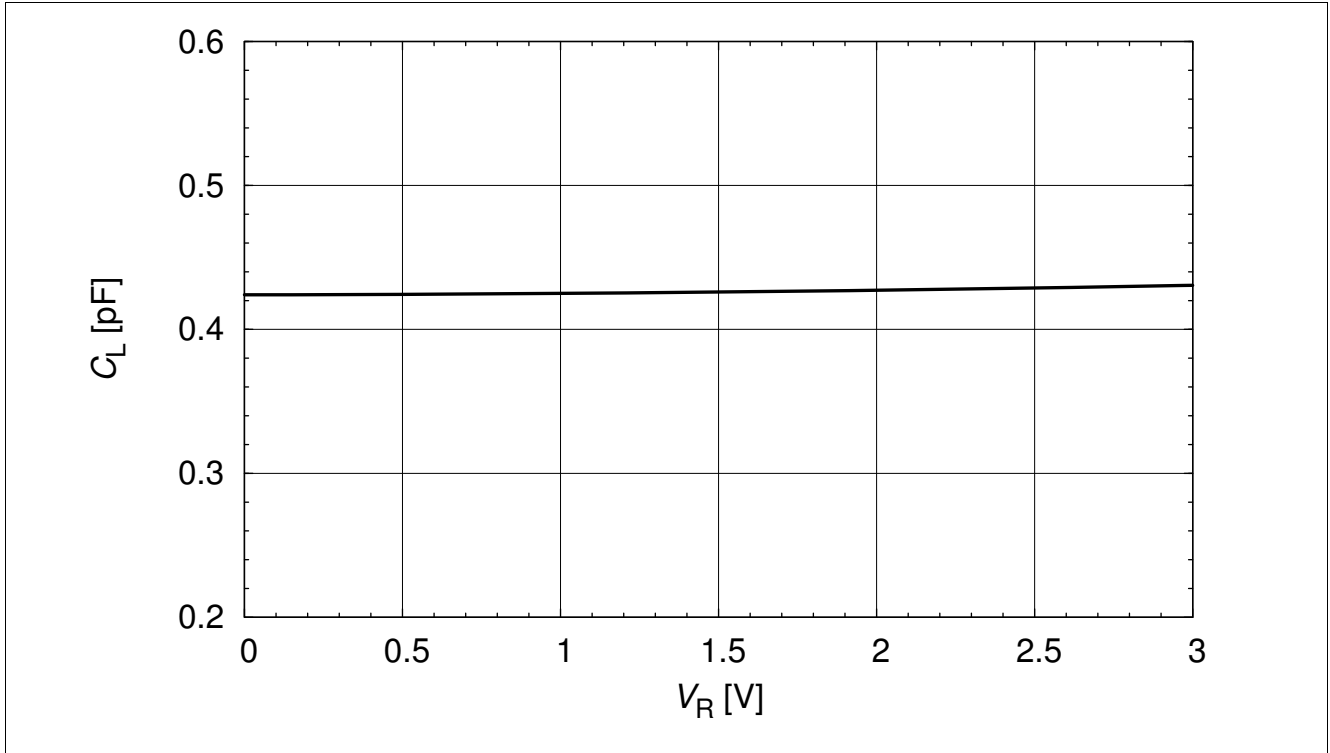


Figure 3 Line capacitance  $C_L=f(V_R)$   $f = 1\text{MHz}$ , from pin 1 to pin 2

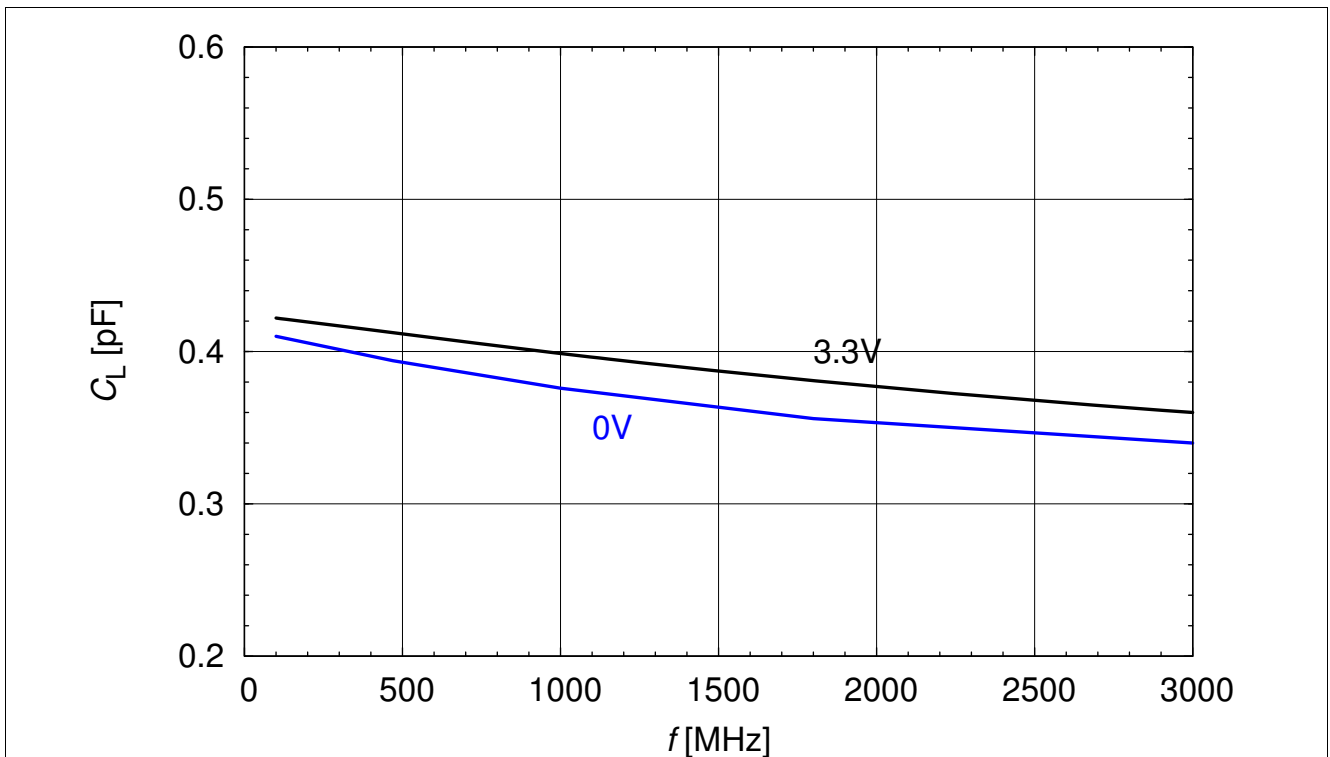


Figure 4 Line capacitance  $C_L=f(f)$ , from pin 1 to pin 2

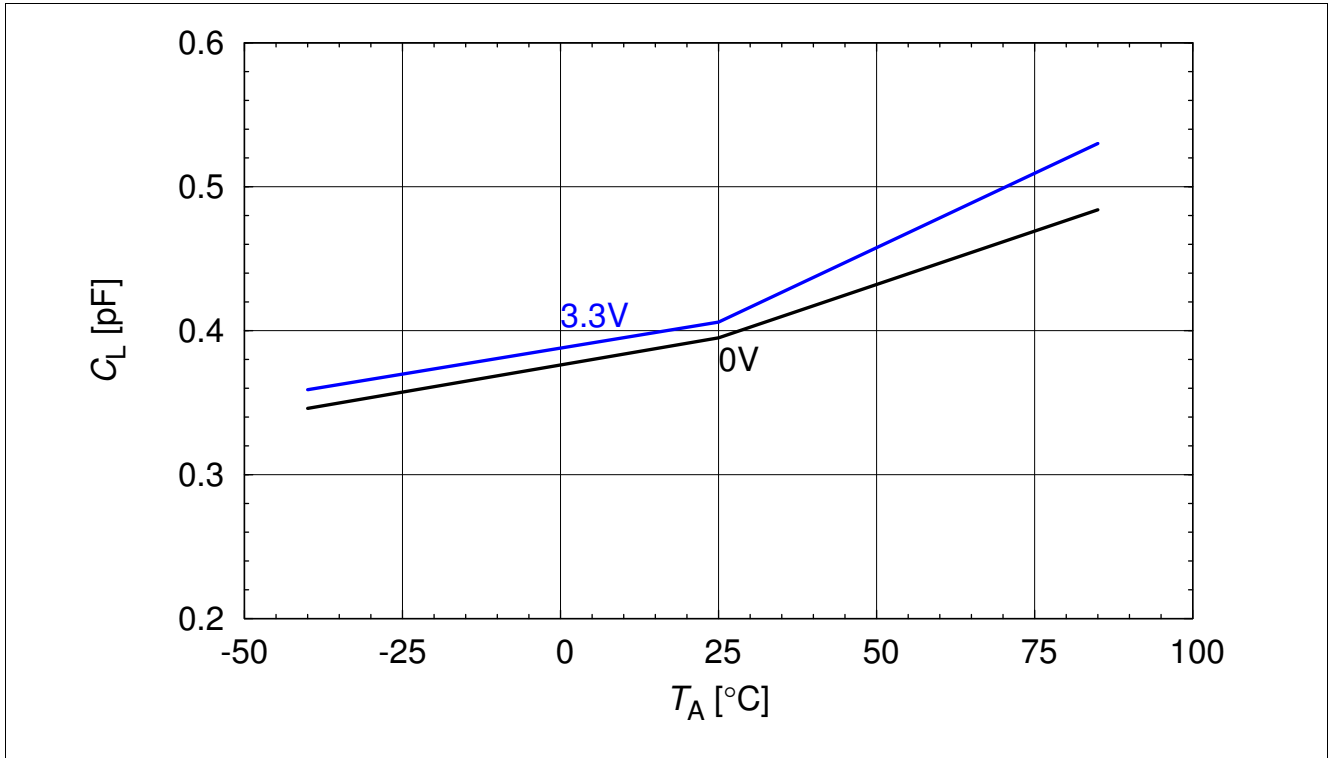


Figure 5 Line capacitance  $C_L=f(T_A)$ , from pin 1 to pin 2

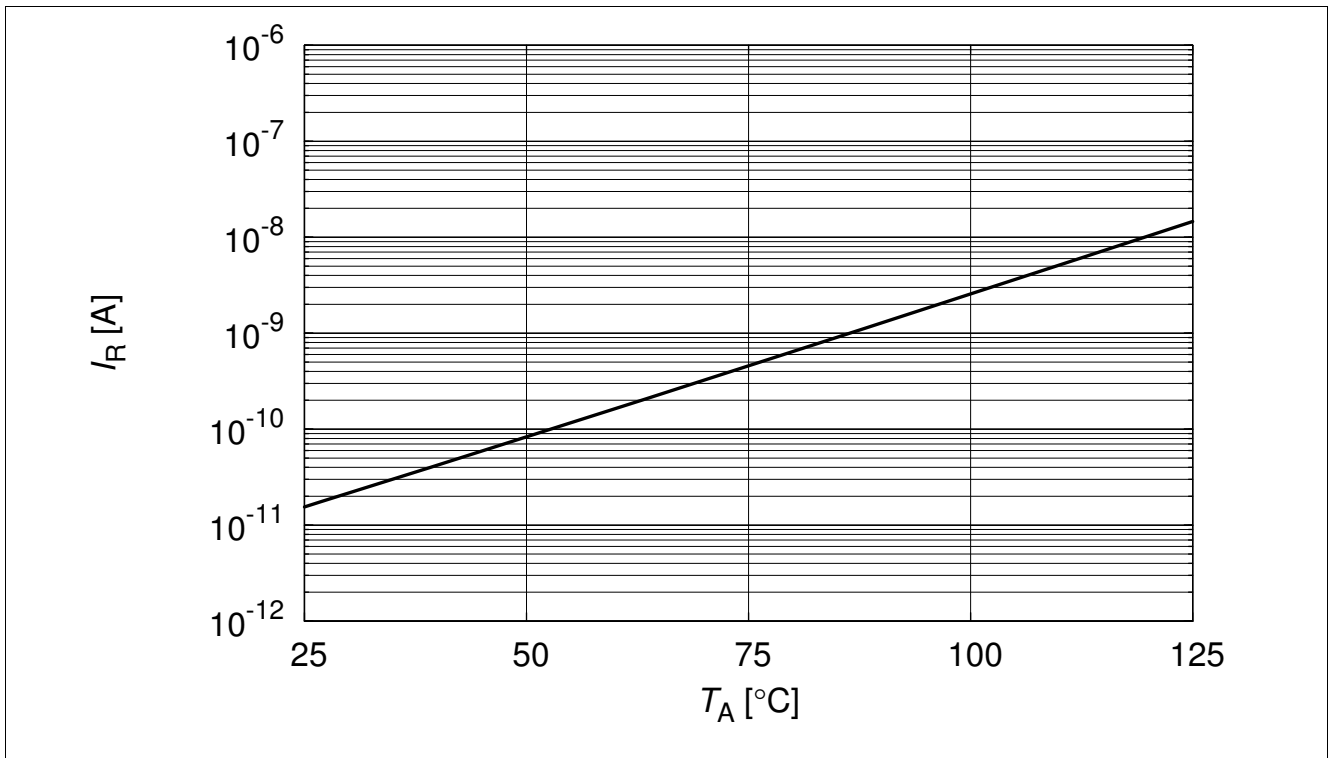


Figure 6 Reverse current  $I_R=f(T_A)$ ,  $V_R=3.3\text{ V}$ , from pin 1 to pin 2

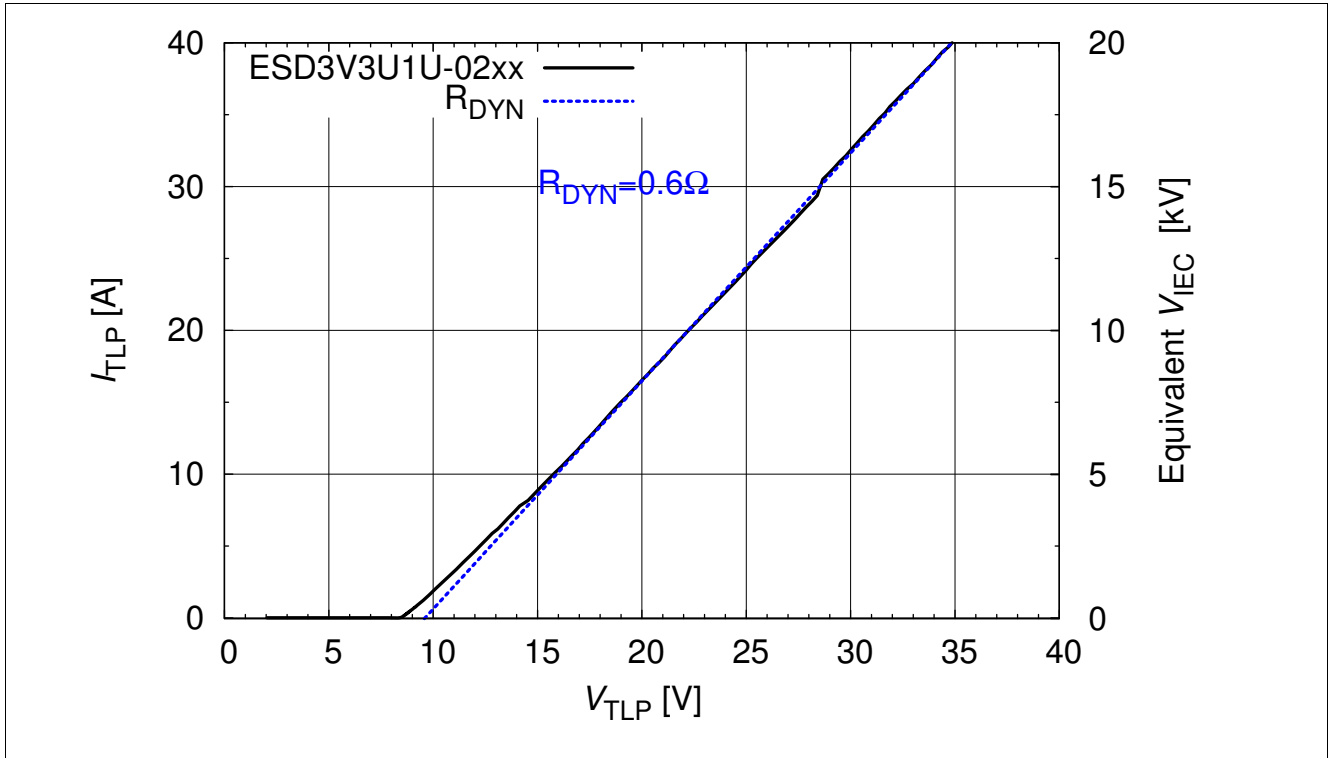


Figure 7 Clamping voltage  $V_{TLP}=f(I_{TLP})$ , from pin 1 to pin 2[1]

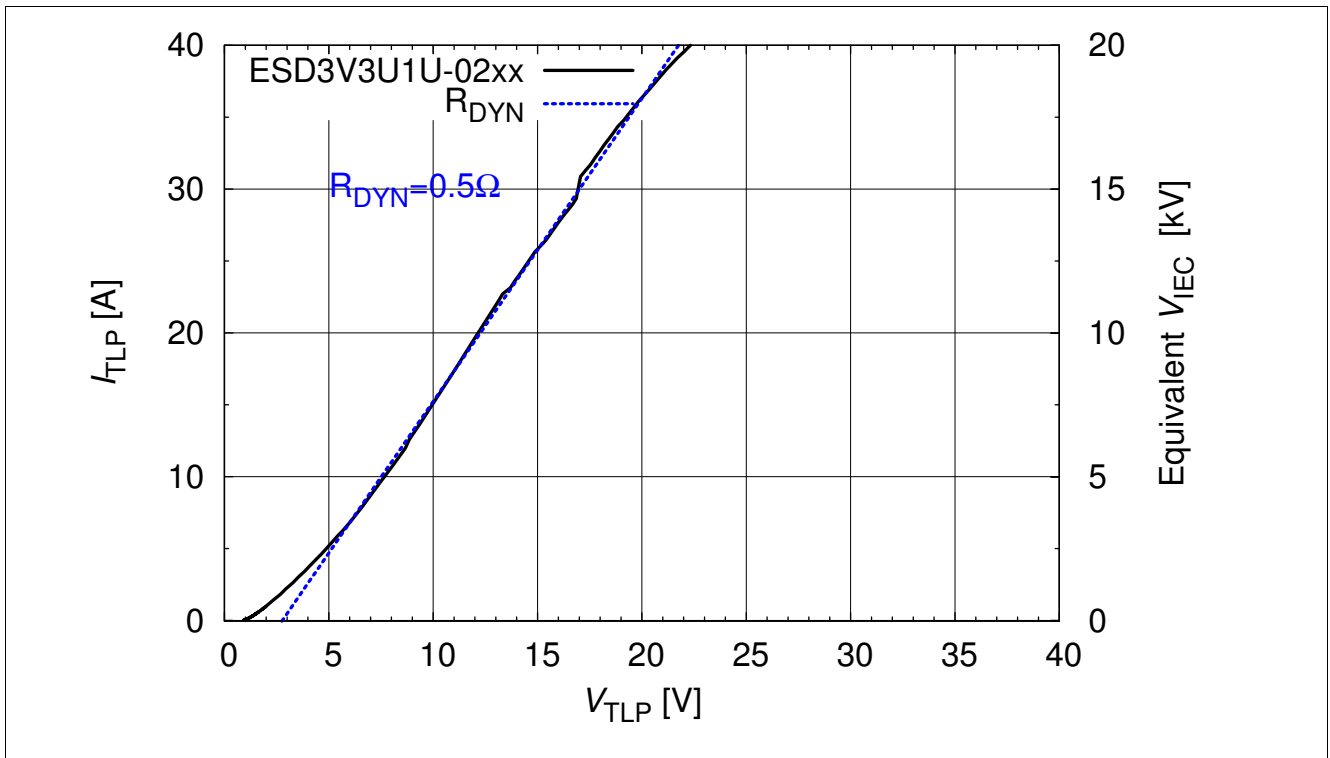


Figure 8 Forward clamping voltage  $V_{TLP}=f(I_{TLP})$ , from pin 2 to pin 1[1]

## 4 Application Information

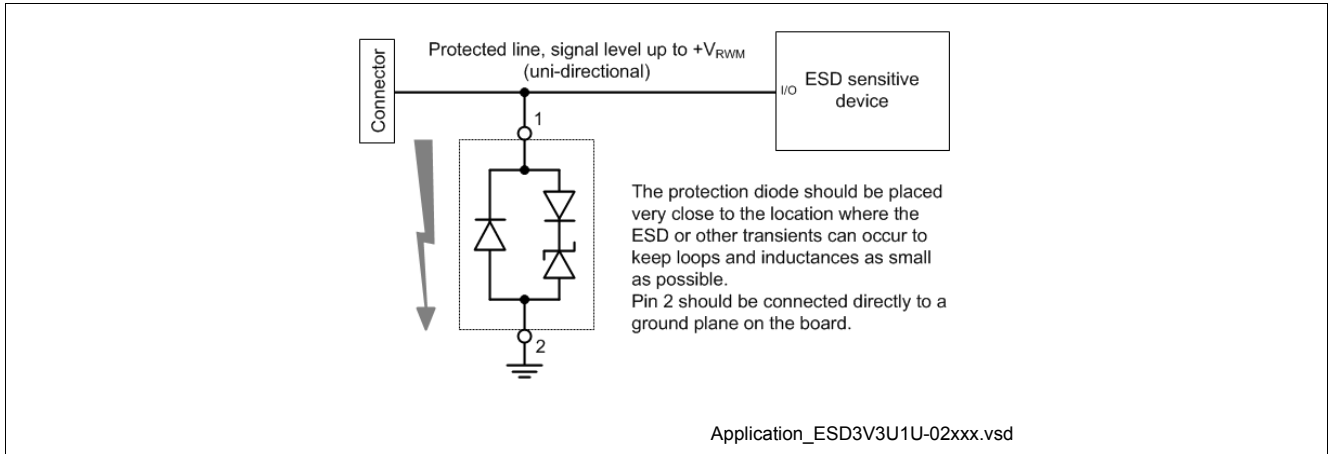


Figure 9 Single line, uni-directional ESD / Transient protection[2]

## 5 Ordering Information Scheme (Examples)

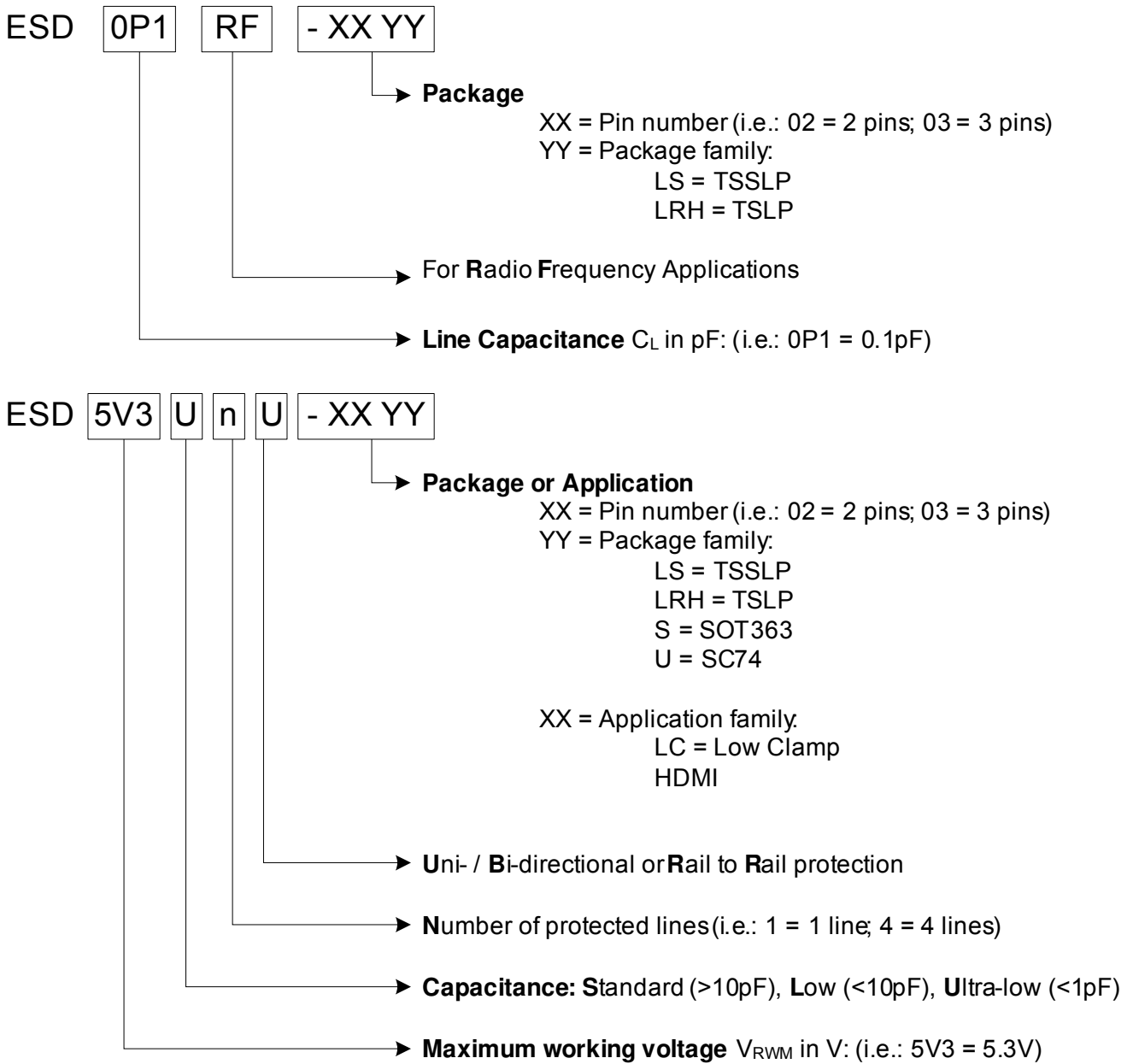


Figure 10 Ordering information scheme

## 6 Package Information

### 6.1 PG-TSSLP-2-1 (mm) [3]

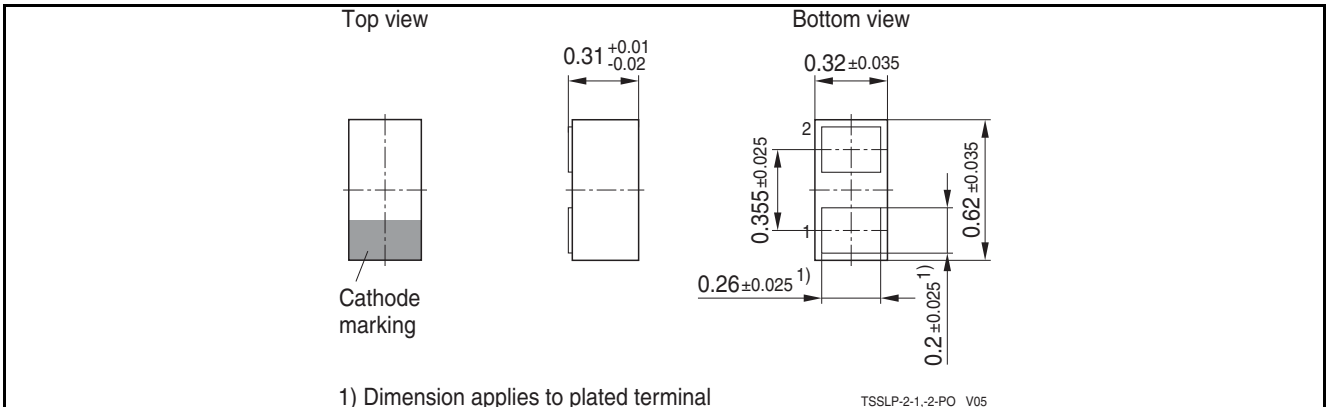


Figure 11 PG-TSSLP-2-1: Package overview

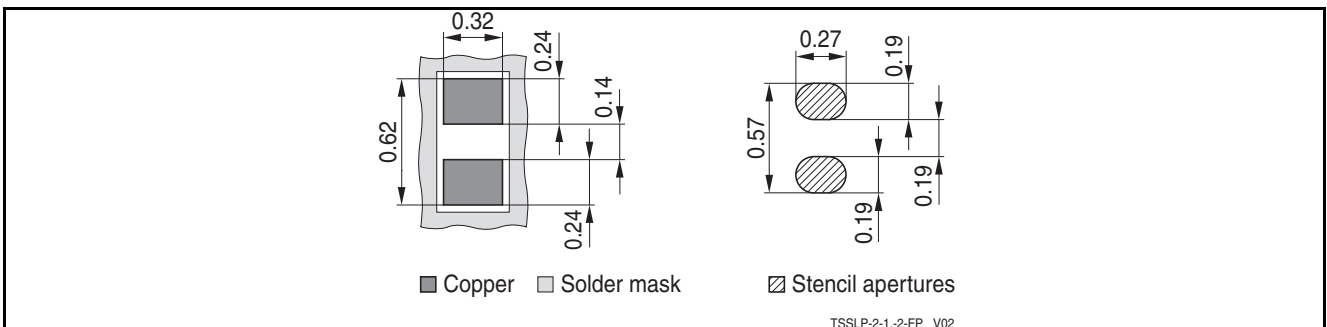


Figure 12 PG-TSSLP-2-1: Footprint

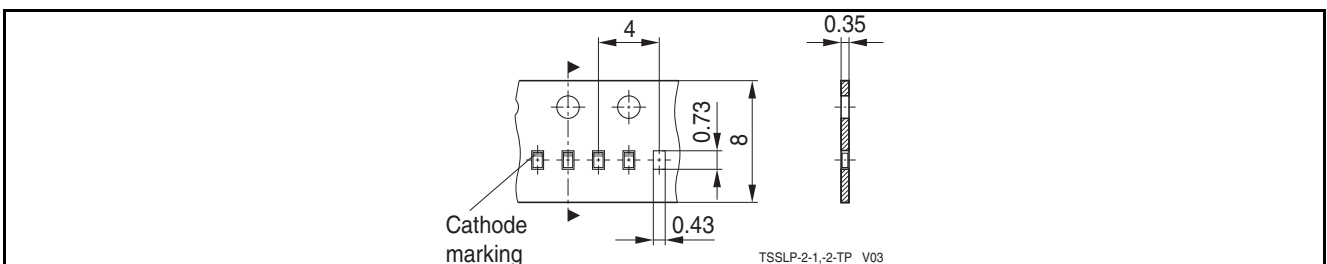


Figure 13 PG-TSSLP-2-1: Packing

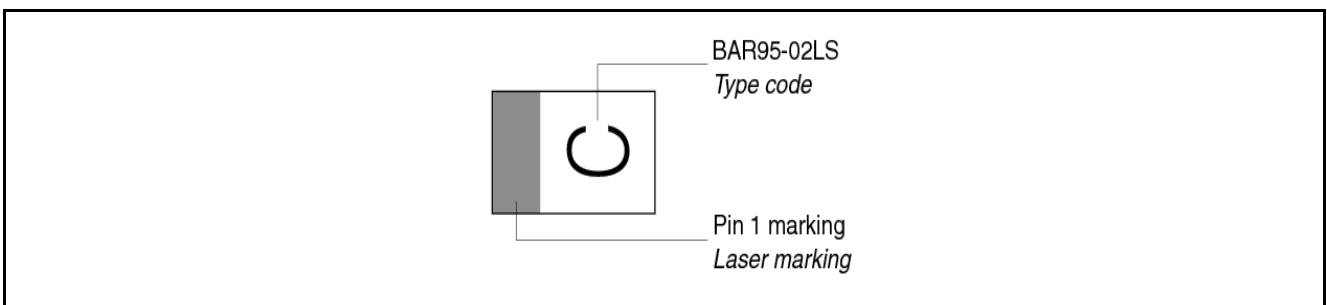


Figure 14 PG-TSSLP-2-1: Marking (example)



6.2 PG-TSLP-2-7 (mm)[3]

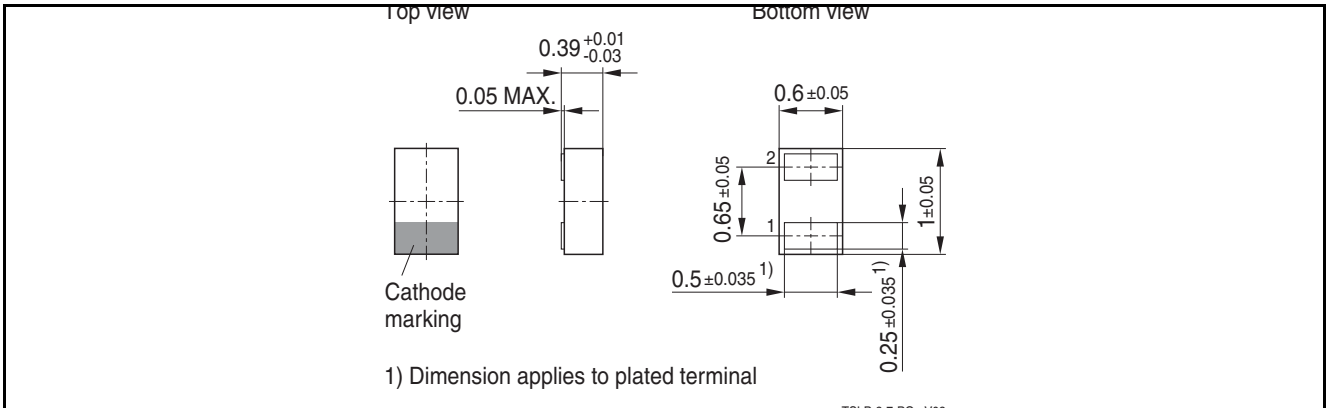


Figure 15 PG-TSLP-2-7: Package overview

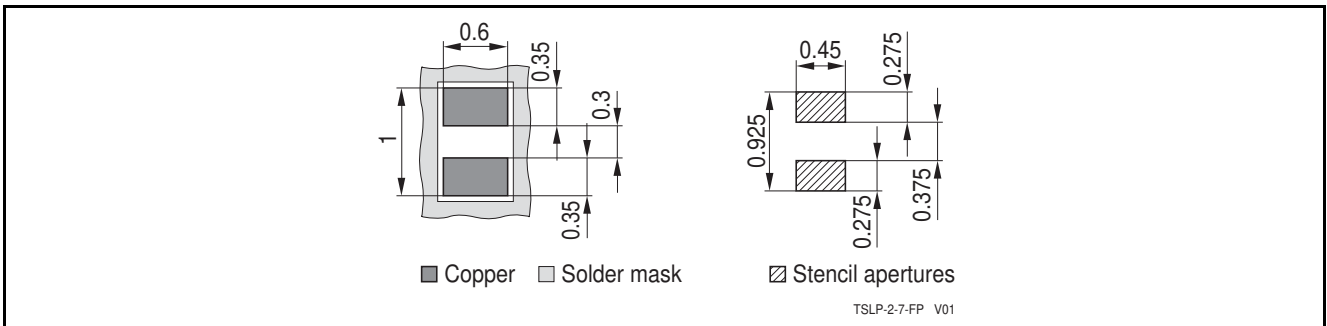


Figure 16 PG-TSLP-2-7: Footprint

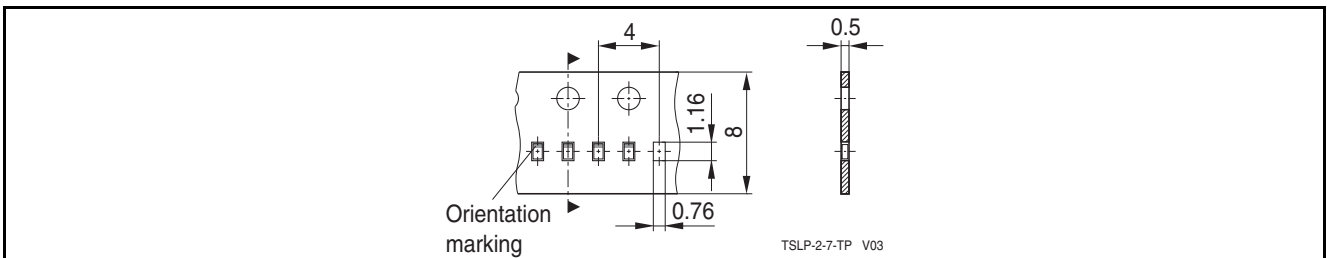


Figure 17 PG-TSLP-2-7: Packing

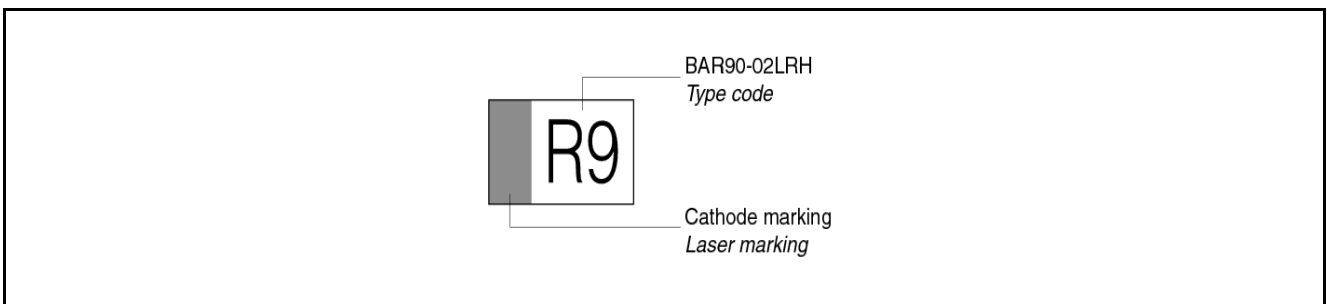


Figure 18 PG-TSLP-2-7: Marking (example)

## Terminology

$C_L$	Line capacitance
EFT	Electrical Fast Transient
ESD	Electrostatic Discharge
HDMI	High Definition Multimedia Interface
IEC	International Electrotechnical Commission
$I_{PP}$	Peak pulse current
$I_R$	Reverse current
$I_{RWM}$	Maximum Reverse working Current
LCD	Liquid Crystal Display
$L_S$	Serial inductance
MDDI	Mobile Display Digital Interface
MIPI	Mobile Industrial Processor Interface
<b>RoHS</b>	Restriction of Hazardous Substances Directive
S-ATA	Serial Advanced Technology Attachment
$T_A$	Ambient temperature
$T_{OP}$	Operation temperature
$t_p$	Pulse duration
$T_{stg}$	Storage temperature
USB	Universal Serial Bus
$V_{BR}$	Breakdown Voltage
$V_{CL}$	Reverse Clamping Voltage
$V_{ESD}$	Electrostatic Discharge Voltage
$V_{FC}$	Forward Clamping Voltage
$V_R$	Reverse Voltage
$V_{RWM}$	Maximum Reverse Working Voltage

**References**

- [1] Infineon AG - **Application Note AN210**: Effective ESD Protection Design at System Level Using VF-TLP Characterization Methodology
- [2] Infineon AG - **Application Note AN140**: ESD Protection for Digital High-Speed Interfaces (HDMI, FireWire, ...) using ESD5V3U1U)
- [3] Infineon AG - Recommendations for PCB Assembly of Infineon TSLP and TSSLP Package

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